

METHOD OF PROCESSING SUBSTRATE, METHOD OF MANUFACTURING
SEMICONDUCTOR DEVICE, PROGRAM, AND SUBSTRATE PROCESSING
APPARATUS

ABSTRACT

A technique includes (a) supplying a substance X to a substrate disposed in a second process chamber, which is in fluid communication with a first process chamber via a loading/unloading port, so that the substance X is adsorbed on the substrate; (b) transferring the substrate on which the substance X is adsorbed from the second process chamber into the first process chamber; and (c) supplying an etching agent to the substrate in the first process chamber and so that the etching agent reacts with the substance X to etch a surface of the substrate.

Fig. 5B